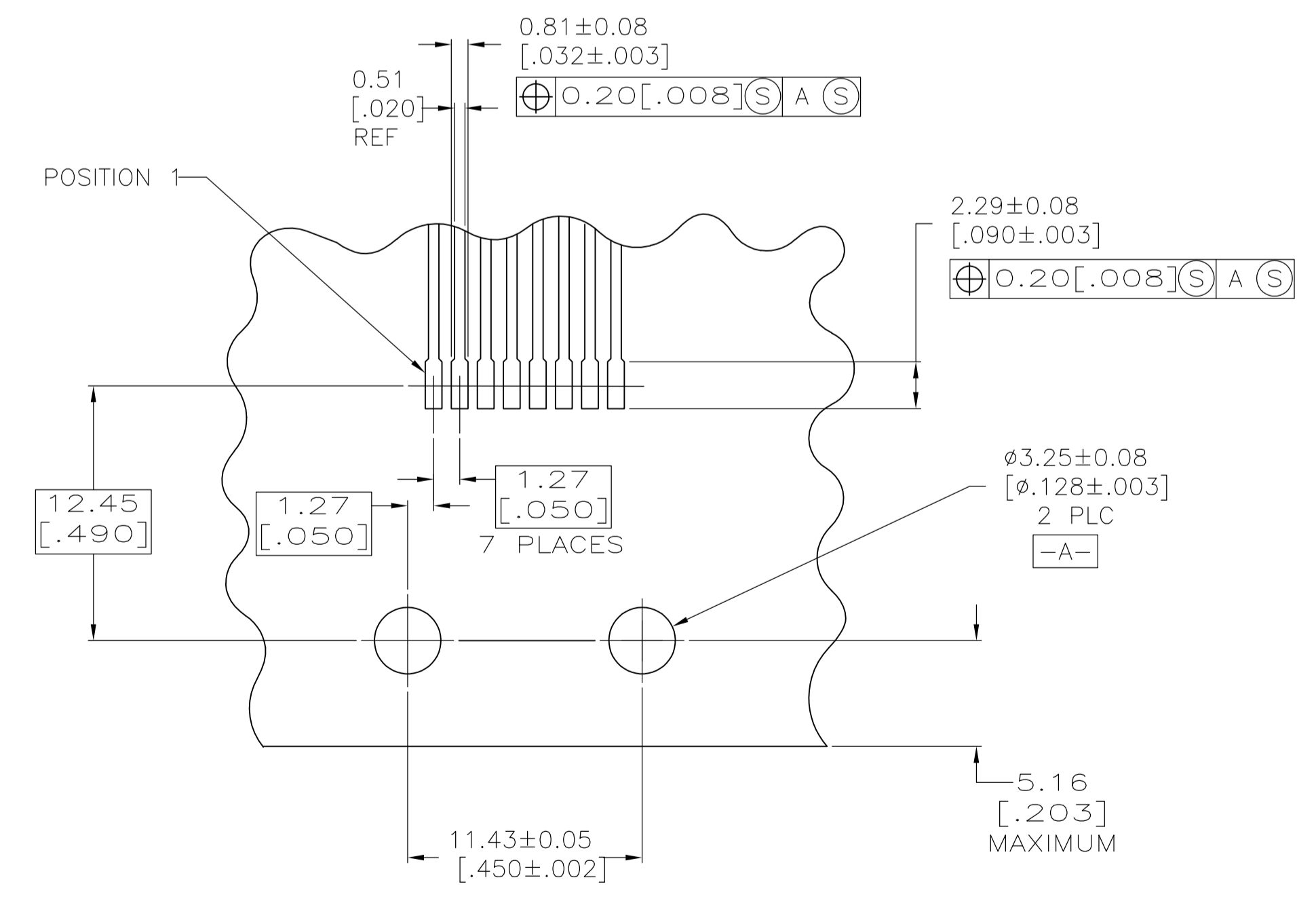
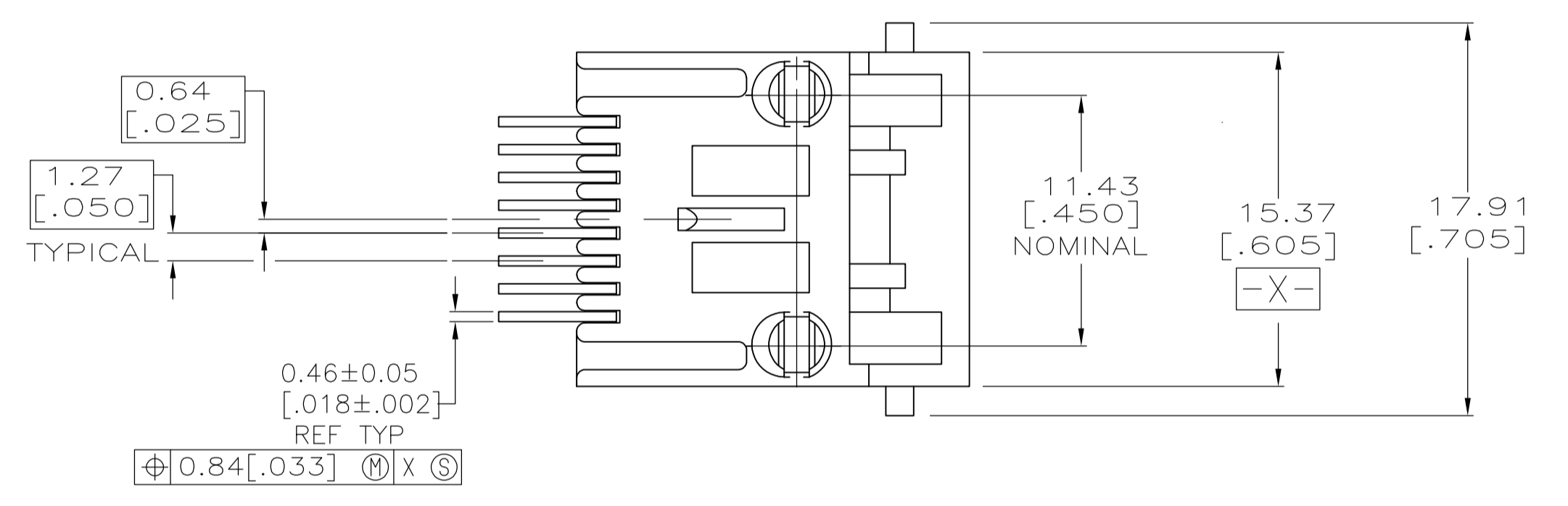
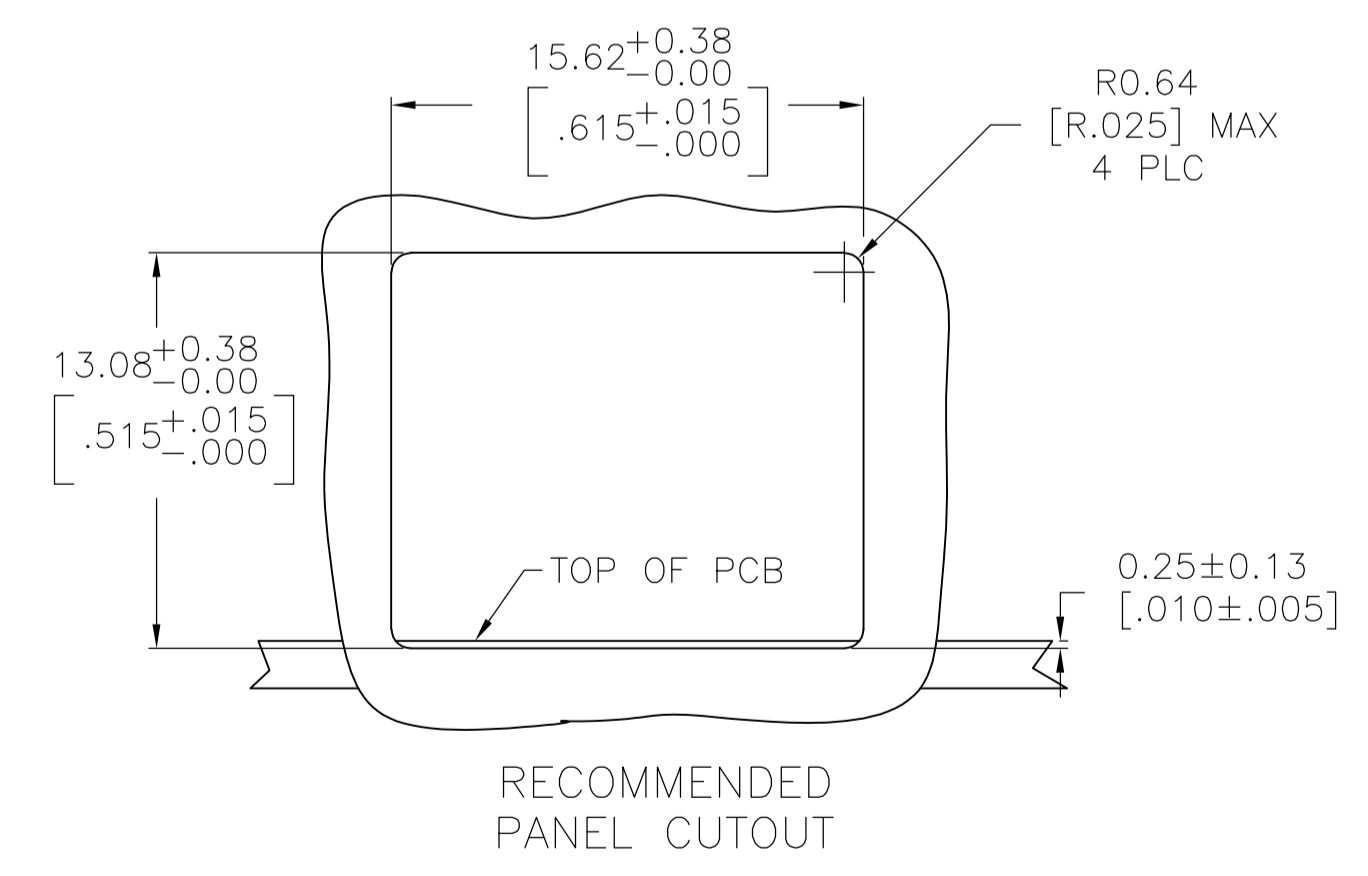


- MATERIAL: HOUSING - HTN MOLDING COMPOUND, 94 VO, COLOR: BLACK  
 TERMINAL - 0.36 [0.014] THICK PHOS-BRONZE PLATE WITH 1.27µm [0.000050] MINIMUM THICK HARD GOLD IN LOCALIZED GOLD PLATE AREA AND 3.81µm [0.000150] MINIMUM THICK MATTE TIN IN SOLDER AREA OVER 1.27µm [0.000050] MINIMUM THICK NICKEL UNDERPLATE.
- CAVITY CONFORMS TO FCC RULES AND REGULATIONS, PART 68, SUBPART F.
- ALL DIMENSIONS SHOWN ARE MAXIMUM UNLESS OTHERWISE SPECIFIED AND ARE PRIOR TO SURFACE MOUNT PROCESSING.
- SNAP-IN RETENTION FEATURE ACCOMMODATES 1.45-1.70 [0.062±0.005] THICK PRINTED CIRCUIT BOARD.



RECOMMENDED PRINTED CIRCUIT BOARD COMPONENT SIDE



RECOMMENDED PANEL CUTOUT

THIS DRAWING IS A CONTROLLED DOCUMENT.		DIN G. ATTADIA - 08/JUN/2005	Tyco Electronics Corporation Harrisburg, PA 17105-3608	
DIMENSIONS: mm [INCHES]		CHK J. WESTMAN	Tyco Electronics Corporation	
TOLERANCES UNLESS OTHERWISE SPECIFIED:		APVD S. FLICKINGER	NAME MODULAR JACK ASSEMBLY, 8 POSITION, LOW PROFILE, RIGHT ANGLE, SURFACE MOUNT, WITH PANEL STOPS	
0 PLC ± -		PRODUCT SPEC	108-1163	
1 PLC ± -		APPLICATION SPEC	114-6040	
2 PLC ± -		SIZE	A1	
3 PLC ± -		CAGE CODE	00779	
4 PLC ± -		DRAWING NO	5555248	
ANGLES ± -		WEIGHT	-	
MATERIAL SEE NOTE 1	FINISH SEE NOTE 1	CUSTOMER DRAWING	SCALE 4:1	SHEET 1 OF 1

单击下面可查看定价，库存，交付和生命周期等信息

[>>TE Connectivity\(泰科\)](#)